

1.6 x 0.8 x 0.95mm Dome Lens Chip LED

OSXX06034C1F

■Features

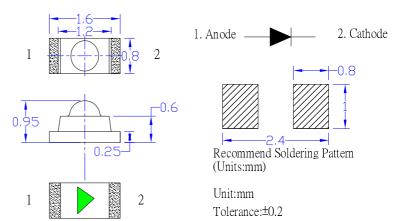
- Single chip
- Super high brightness of surface mount LED
- Compact package outline (LxWxT) of 1.6mm x 0.8mm x 0.95mm
- Compatible to IR reflow soldering.

■Applications

Backlighting (switches, keys, etc.)
Marker lights (e.g. steps, exit ways, etc.)

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Outline Dimension

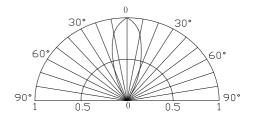


■Absolute Maximum Rating

T4	Symbo	Value	Unit		
Item	1	B5/G5	G8/Y5/O5/R5	Unit	
DC Forward Current	I_{F}	30	25	mA	
Pulse Forward Current*	I_{FP}	100	80	mA	
Reverse Voltage	V_R	5	5	V	
Power Dissipation	PD	102	60	mW	
Operating Temperature	Topr	-40	$^{\circ}\mathbb{C}$		
Storage Temperature	Tstg	-4	$^{\circ}\mathbb{C}$		

Tsol

■Directivity



Lead Soldering Temperature

■ Electrical -Optical Characteristics

(Ta=25°C)

260°€/5sec

(Ta=25°C)

			$V_{F}(V)$		$I_R(\mu A)$	Iv(mcd)		λD(nm)		2θ1/2(deg)				
Part Number Color		Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.		
		I _F =20mA		V _R =5V	I _F =20mA									
OSB5060341F	Blue	B5		2.8	3.1	3.4	10	150	350	-	460	465	470	35
OSG5060341F	True Green	G5		2.8	3.1	3.4	10	1300	2500	-	518	521	526	35
OSG8060341F	Yellow green	G8		1.8	2.1	2.4	10	70	150	-	565	570	575	35
OSY5060341F	Yellow	Y5		1.8	2.1	2.4	10	200	400	-	585	590	595	35
OSO5060341F	Orange	O5		1.8	2.1	2.4	10	200	400	-	600	605	610	35
OSR5060341F	Red	R5		1.8	2.1	2.4	10	200	400	-	617	621	625	35

^{*1} Tolerance of measurements of chromaticity coordinate is $\pm 10\%$

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^{*}Pulse width Max 0.1ms, Duty ratio max 1/10

^{*2} Tolerance of measurements of dominant wavelength is ± 1 nm

^{*3} Tolerance of measurements of luminous intensity is ±15%

^{*4} Tolerance of measurements of forward voltage is±0.1V



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■ Cautions:

- 1. After open the package, the LED's floor life is 1 year under 30° C or less and 60%RH or less (MSL:2).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.
- 8. OPTOSUPPLY will not do 4M change without advance consultation.

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